Urban Shield Micellar Conditioner

Bust your dull, tired, and damaged hair with this light, moisturizing conditioner formula and rescue your day.

Clear conditioner gently conditions hair without weighing it down and leaves hair full and shiny. Contains ingredients that moisturize the scalp and have been shown to provide protection from pollution.



Cellosize™ PCG-10: Nonionic, water-soluble polymer that can thicken, suspend, bind, emulsify, form films, stabilize, disperse, retain water, and provide protective colloid action. Outstanding tolerance for dissolved electrolytes.

DOWSIL™ CE-1874

Microemulsion: For use in clear, standard, sulfate-free shampoos and conditioners. Provides improved sensory feel, enhanced volume, damage repair, color protection, and shine.

UCARE™ Polymer JR-400P:

Light to medium conditioning with no volume-down effects.



Niacinamide PC: Studies suggest it has anti-inflammatory activity on blemished skin; improves skin moisturization and the appearance of aging skin; provides protection against blue light, oxidative stress, and urban pollution.



Maquat® CETAC-30%: Naturally plant derived cetyl trimethyl ammonium chloride in water with excellent substantive and anti-static properties that imparts exceptional conditioning, and detangling.















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СОМРО	COMPOSITION				
Phase	Ingredients	% by Wt	Trade Name	Supplier	
	Water, Deionized	86.700			
	Hydroxyethyl Cellulose	0.900	Cellosize™ PCG-10	Nexeo / Dow	
	EDTA (Tetrasodium salt)	0.200	Versene™ 220	Nexeo / Dow	
Α	Niacinamide	2.000	Niacinamide PC	Nexeo / DSM	
	Saccharide Isomerate (and) Aqua (and) Citric Acid (and) Sodium Citrate	0.500	PENTAVITIN®	DSM	
	Caprylhydroxamic Acid (and) 1,2-Hexanediol (and) Propanediol	1.000	Spectrastat™ PHL	Nexeo / Inolex	
	Cetrimonium Chloride	3.000	Maquat® CETAC-30%	Nexeo / Pilot	
В	Propylene Glycol	2.000	Propylene Glycol USP/EP	Nexeo / Dow	
Ь	Polyquaternium-10	0.150	UCARE™ Polymer JR-400P	Nexeo / Dow	
С	PEG-7 Dimethicone (and) Laureth-7 (and) Polysorbate 20	2.000	DOWSIL™ CE-1874	Nexeo / Dow	
D	Fragrance	0.200	Avocado Mint Fragrance	Chemia	
D	Polysorbate 20	1.200	Alkamuls® PSML-20	Nexeo / Solvay	
E	Citric Acid (33% solution in water)	0.150	Citric Acid, Anhydrous FCC USP	Nexeo	

PROCEDURE		PROPERTIES	FORMULATION NO.	
	Add phase A ingredients sequentially with mixing and continue mixing until thickened and clear.	pH- 5.5-6.0	NL0027-106-1	

- Add phase A ingredients sequentially with mixing and continue mixing until thickened and clear.
- Premix phase B and add to phase A with mixing.
- Add phase C to phase AB with mixing.
- Pre-mix phase D ingredients and add to phase ABC.
- Adjust pH to 5.5-6.0 if needed with citric acid.

Brookfield Viscosity: 6500 cP/ 4700 cP/ 3900 cP @ 10rpm/20rpm/30rpm w/ #5 Spindle (21°C)

TECHNICAL ASSISTANCE

For more information, to place an order, or request samples, contact Nexeo Solutions at 281.982.9447 or visit www.nexeosolutions.com.

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